

**PCN #207**  
**Notification Date:**  
**March 2, 2021**

**Product / Process Change Notice**

**Parts Affected:**

The following SOT-223 transistors are affected:  
CBCP69  
CEN1220  
CZT3019

**Extent of Change:**

The die attach method used in the assembly process is changing from eutectic to soft solder.

**Reason for Change:**

The soft solder die attach method is better suited for devices of larger die size.

**Effect of Change:**

This change does not affect the fit, form or function of the devices.

**Qualification:**

Test	Condition	Duration	Failure rate
Temperature Cycling (T.C.)	TA= -55+0°C/-10°C 15min(Min) TA= +150+15°C/-0°C 15min(Min) Transfer time less than 1min. The load should reach temp. within 15min	1000 Cycles	0/77
Resistance to Solder Heat (R.S.H.)	T =260°C ±5°C Dwell time = 10 sec.	1 Cycle	0/5
Thermal Shock Test (T.S.T.)	TA=0°C (5 min) ~ +100°C (5 min)	100 Cycles	0/77

**Effective Date of Change:**

Existing inventory will be shipped until depleted.

**Sample Availability:**

Please contact your salesperson or manufacturer’s representative for samples.



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[www.centrialsemi.com](http://www.centrialsemi.com)

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<https://www.centrialsemi.com/process-change-notices>

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As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor's Product/Process Change Notification (PCN).

Company Name:	
Address:	
Printed Name:	
Title:	
Signature:	
Date:	